

Molded Interconnect Device (MID) Market based on by Product Type (Antennae & Connectivity, Sensor),by Process (Laser Direct Structuring, Two-shot Molding), by Industry (Consumer Electronics, Telecommunication, Medical) and Geography– Global Forecast up to 2030

<https://marketpublishers.com/r/M916E9AECAF BEN.html>

Date: November 2023

Pages: 124

Price: US\$ 4,500.00 (Single User License)

ID: M916E9AECAF BEN

Abstracts

In order to estimate the present size of the moulded interconnect device (MID) market, the study covered four main tasks. To gather data about the market, as well as its parent and peer markets, in-depth secondary research was conducted. The following stage involved conducting primary research to confirm these conclusions, hypotheses, and sizing with industry experts throughout the value chain. Two methodologies were utilised to approximate the overall market size: top-down and bottom-up. The size of the market for each section and subsegment was then estimated using data triangulation and market breakdown.

Numerous primary sources from the supply and demand sides were questioned during the main research phase to gather crucial qualitative and quantitative data for this report. Industry specialists including CEOs, VPs, marketing directors, directors of technology and innovation, and associated executives from significant firms and organisations in the moulded interconnect device (MID) sector were the main sources from the supply side. Following the completion of market engineering, which involved the computation of market statistics, market breakdown, market size estimates, market forecasting, and data triangulation, a significant amount of primary research was carried out in order to collect data and confirm and validate the crucial figures that were determined.

Several data triangulation techniques, in addition to top-down and bottom-up approaches, have been used throughout the market engineering process to estimate and validate the size of the dependent submarkets described in this study, as well as the moulded interconnect device (MID) market.

Molded Interconnect Device (MID) Market based on Product Type:

Antennae & Connectivity Modules

Sensors

Connectors & Switches

Lighting Systems

Others

Molded Interconnect Device (MID) Market based on Process:

Laser Direct Structuring (LDS)

Two-Shot Molding

Film Techniques

Molded Interconnect Device (MID) Market, by Vertical:

Telecommunications

Consumer Electronics

Automotive

Medical

Industrial

Military & Aerospace

Molded Interconnect Device (MID) Market based on Geography:

North America

US

Canada

Europe

Germany

UK

France

Italy

Spain

Rest of Europe (RoE)

Asia Pacific (APAC)

China

Japan

India

Australia

South Korea

Rest of Asia Pacific (RoAPAC)

Latin America (LATAM)

Brazil

Argentina

Rest of South America

Middle East and Africa (MEA)

UAE

Turkey

Saudi Arabia

South Africa

Rest of Middle East & Africa

The market for moulded connecting devices is divided into product categories such as lighting systems, sensors, connectors & switches, antennas & connectivity modules, and others. The category that generated the largest revenue share in the moulded interconnect device market in 2021 was antennas & connectivity modules. MIDs allow for the creation of new functionality as well as the downsizing of products because they can integrate mechanical and electrical components into nearly any type of connecting device.

The moulded interconnect device market is divided into three segments based on process: film methods, two-shot moulding, and laser direct structuring (LDS). In 2021, the moulded interconnect device market had a sizable revenue share from the two-shot moulding segment. A reliable and well-established technique for creating MIDs that is both affordable and consistent is two-shot moulding. The part is being made in two-shot moulding using two distinct moulding cycles, various thermostatic polymers, and an electroless plating procedure.

The market for moulded interconnect devices is divided into the following vertical segments: consumer electronics, automotive, medical, industrial, military & aerospace,

and telecommunications. With the largest revenue share in the moulded interconnect device market in 2021, the consumer electronics category held the top spot. Electronic gadgets intended for daily use, such as those for entertainment, communications, and workplace productivity, are known as consumer electronics. Consumer electronics include almost all electronic equipment used for work, play, and communication.

The cloud native storage market is examined in North America, Europe, Asia Pacific, and Latin America based on region. The market for moulded interconnect devices saw its highest revenue share in the Asia Pacific region in 2021. The main causes of this include a number of Asian OEMs as well as producers of semiconductor devices and goods. In especially in South Korea, Taiwan, and China, the area has excelled in offering the most cutting-edge semiconductor fabrication services as well as electronic system assembly services. In addition, semiconductor electronics manufacturers gain a great deal from outsourcing their production to places like Taiwan and China.

This report illustrates the most vital attributes of the Molded Interconnect Device (MID) Market, which are driving and providing opportunities.

This research gives an in-depth analysis of the Molded Interconnect Device (MID) Market growth on the basis of several segments in the market.

This report presents the predictions of the past and present trends of the Molded Interconnect Device (MID) Market.

This study also presents the competitive analysis, such as key strategies and capabilities of major players of the Molded Interconnect Device (MID) Market.

Contents

1. EXECUTIVE SUMMARY

2. INDUSTRY OUTLOOK

2.1. Industry Overview

2.2. Industry Trends

3. MARKET SNAPSHOT

3.1. Market Definition

3.2. Market Outlook

3.2.1. Porter Five Forces

3.3. Related Markets

4. MARKET CHARACTERISTICS

4.1. Market Overview

4.2. Market Segmentation

4.3. Market Dynamics

4.3.1. Drivers

4.3.2. Restraints

4.3.3. Opportunities

4.4. DRO - Impact Analysis

5. PRODUCT TYPE: MARKET SIZE & ANALYSIS

5.1. Overview

5.2. Antennae & Connectivity Modules

5.3. Sensors

5.4. Connectors & Switches

5.5. Lighting Systems

5.6. Others

6. PROCESS: MARKET SIZE & ANALYSIS

6.1. Overview

- 6.2. Laser Direct Structuring (LDS)
- 6.3. Two-Shot Molding
- 6.4. Film Techniques

7. VERTICAL : MARKET SIZE & ANALYSIS

- 7.1. Overview
- 7.2. Telecommunications
- 7.3. Consumer Electronics
- 7.4. Automotive
- 7.5. Medical
- 7.6. Industrial
- 7.7. Military & Aerospace

8. GEOGRAPHY: MARKET SIZE & ANALYSIS

- 8.1. Overview
- 8.2. North America (U.S., Mexico, Canada)
- 8.3. Europe (France, Germany, UK, Italy, Netherlands, Spain, Russia, Rest of Europe)
- 8.4. Asia Pacific (Japan, China, India, Australia, South East Asia, Rest of APAC)
- 8.5. Latin America (Brazil, Argentina)
- 8.6. Middle East & Africa (Saudi Arabia, UAE, South Africa, Rest of Middle East and Africa)

9. COMPETITIVE LANDSCAPE

- 9.1. Competitor Comparison Analysis
- 9.2. Market Developments
 - 9.2.1. Mergers and Acquisitions, Legal, Awards, Partnerships
 - 9.2.2. Product Launches and execution

10. VENDOR PROFILES

- 10.1. Molex (US)
 - 10.1.1. Overview
 - 10.1.2. Financial Overview
 - 10.1.3. Product Offerings
 - 10.1.4. Developments
 - 10.1.5. Business Strategy

10.2. TE Connectivity (Switzerland)

- 10.2.1. Overview
- 10.2.2. Financial Overview
- 10.2.3. Product Offerings
- 10.2.4. Developments
- 10.2.5. Business Strategy

10.3. Amphenol Corporation (US)

- 10.3.1. Overview
- 10.3.2. Financial Overview
- 10.3.3. Product Offerings
- 10.3.4. Developments
- 10.3.5. Business Strategy

10.4. LPKF LASER & ELECTRONICS (GERMANY)

- 10.4.1. Overview
- 10.4.2. Financial Overview
- 10.4.3. Product Offerings
- 10.4.4. Developments
- 10.4.5. Business Strategy

10.5. Harting (Germany)

- 10.5.1. Overview
- 10.5.2. Financial Overview
- 10.5.3. Product Offerings
- 10.5.4. Developments
- 10.5.5. Business Strategy

10.6. Arlington Plating Company (US)

- 10.6.1. Overview
- 10.6.2. Financial Overview
- 10.6.3. Product Offerings
- 10.6.4. Developments
- 10.6.5. Business Strategy

10.7. MID Solutions (Germany)

- 10.7.1. Overview
- 10.7.2. Financial Overview
- 10.7.3. Product Offerings
- 10.7.4. Developments
- 10.7.5. Business Strategy

10.8. 2E Mechatronik (Germany)

- 10.8.1. Overview
- 10.8.2. Financial Overview

- 10.8.3. Product Offerings
- 10.8.4. Developments
- 10.8.5. Business Strategy
- 10.9. KYOCERA AVX (US)
 - 10.9.1. Overview
 - 10.9.2. Financial Overview
 - 10.9.3. Product Offerings
 - 10.9.4. Developments
 - 10.9.5. Business Strategy
- 10.10. Taoglas (Dublin)
 - 10.10.1. Overview
 - 10.10.2. Financial Overview
 - 10.10.3. Product Offerings
 - 10.10.4. Developments
 - 10.10.5. Business Strategy

11. ANALYST OPINION

12. ANNEXURE

- 12.1. Report Scope
- 12.2. Market Definitions
- 12.3. Research Methodology
 - 12.3.1. Data Collation and In-house Estimation
 - 12.3.2. Market Triangulation
 - 12.3.3. Forecasting
- 12.4. Report Assumptions
- 12.5. Declarations
- 12.6. Stakeholders
- 12.7. LDK Laser & Electronics (Germany)
- 12.8. Abbreviations

Tables

TABLE 1. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 2. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR ANTENNAE & CONNECTIVITY MODULES, BY GEOGRAPHY, 2021-2030 (USD BILLION)

TABLE 3. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR

SENSORS, BY GEOGRAPHY, 2021-2030 (USD BILLION)

TABLE 4. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR CONNECTORS & SWITCHES, BY GEOGRAPHY, 2021-2030 (USD BILLION)

TABLE 5. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR LIGHTING SYSTEMS, BY GEOGRAPHY, 2021-2030 (USD BILLION)

TABLE 6. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR OTHERS, BY GEOGRAPHY, 2021-2030 (USD BILLION)

TABLE 7. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 8. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR LASER DIRECT STRUCTURING (LDS), 2021-2030 (USD BILLION)

TABLE 9. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR TWO-SHOT MOLDING, BY GEOGRAPHY, 2021-2030 (USD BILLION)

TABLE 10. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR FILM TECHNIQUES, 2021-2030 (USD BILLION)

TABLE 11. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY VERTICAL, 2021-2030 (USD BILLION)

TABLE 12. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR TELECOMMUNICATIONS, 2021-2030 (USD BILLION)

TABLE 13. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR CONSUMER ELECTRONICS, BY GEOGRAPHY, 2021-2030 (USD BILLION)

TABLE 14. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR AUTOMOTIVE, 2021-2030 (USD BILLION)

TABLE 15. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR MEDICAL, 2021-2030 (USD BILLION)

TABLE 16. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR INDUSTRIAL, 2021-2030 (USD BILLION)

TABLE 17. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR MILITARY & AEROSPACE, 2021-2030 (USD BILLION)

TABLE 18. NORTH AMERICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY COUNTRY, 2021-2030 (USD BILLION)

TABLE 19. NORTH AMERICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 20. NORTH AMERICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 21. U.S MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 22. U.S MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 23. CANADA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 24. CANADA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 25. MEXICO MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 26. MEXICO MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 27. EUROPE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY COUNTRY, 2021-2030 (USD BILLION)

TABLE 28. EUROPE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 29. EUROPE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 30. GERMANY MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 31. GERMANY MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 32. U.K MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 33. U.K MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 34. FRANCE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 35. FRANCE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 36. ITALY MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 37. ITALY MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 38. SPAIN MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 39. SPAIN MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 40. ROE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 41. ROE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 42. ASIA PACIFIC MOLDED INTERCONNECT DEVICE (MID) MARKET

VALUE, BY COUNTRY, 2021-2030 (USD BILLION)

TABLE 43. ASIA PACIFIC MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 44. ASIA PACIFIC MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 45. CHINA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 46. CHINA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 47. INDIA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 48. INDIA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 49. JAPAN MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 50. JAPAN MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 51. REST OF APAC MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 52. REST OF APAC MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 53. LATIN AMERICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 54. LATIN AMERICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 55. BRAZIL MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 56. BRAZIL MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 57. ARGENTINA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 58. ARGENTINA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 59. MIDDLE EAST AND AFRICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 60. MIDDLE EAST AND AFRICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 61. SAUDI ARABIA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 62. SAUDI ARABIA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 63. UAE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 64. UAE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 65. REST OF MIDDLE EAST AND AFRICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

TABLE 66. REST OF MIDDLE EAST AND AFRICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

TABLE 67. MOLEX (US): FINANCIALS

TABLE 68. MOLEX (US): PRODUCTS & SERVICES

TABLE 69. MOLEX (US): RECENT DEVELOPMENTS

TABLE 70. TE CONNECTIVITY (SWITZERLAND): FINANCIALS

TABLE 71. TE CONNECTIVITY (SWITZERLAND): PRODUCTS & SERVICES

TABLE 72. TE CONNECTIVITY (SWITZERLAND): RECENT DEVELOPMENTS

TABLE 73. AMPHENOL CORPORATION (US): FINANCIALS

TABLE 74. AMPHENOL CORPORATION (US): PRODUCTS & SERVICES

TABLE 75. AMPHENOL CORPORATION (US): RECENT DEVELOPMENTS

TABLE 76. LPKF LASER & ELECTRONICS (GERMANY): FINANCIALS

TABLE 77. LPKF LASER & ELECTRONICS (GERMANY): PRODUCTS & SERVICES

TABLE 78. LPKF LASER & ELECTRONICS (GERMANY): RECENT DEVELOPMENTS

TABLE 79. HARTING (GERMANY): FINANCIALS

TABLE 80. HARTING (GERMANY): PRODUCTS & SERVICES

TABLE 81. HARTING (GERMANY): RECENT DEVELOPMENTS

TABLE 82. ARLINGTON PLATING COMPANY (US): FINANCIALS

TABLE 83. ARLINGTON PLATING COMPANY (US): PRODUCTS & SERVICES

TABLE 84. ARLINGTON PLATING COMPANY (US): RECENT DEVELOPMENTS

TABLE 85. MID SOLUTIONS (GERMANY): FINANCIALS

TABLE 86. MID SOLUTIONS (GERMANY): PRODUCTS & SERVICES

TABLE 87. MID SOLUTIONS (GERMANY): RECENT DEVELOPMENTS

TABLE 88. 2E MECHATRONIC (GERMANY): FINANCIALS

TABLE 89. 2E MECHATRONIC (GERMANY): PRODUCTS & SERVICES

TABLE 90. 2E MECHATRONIC (GERMANY): RECENT DEVELOPMENTS

TABLE 91. KYOCERA AVX (US): FINANCIALS

TABLE 92. KYOCERA AVX (US): PRODUCTS & SERVICES

TABLE 93. KYOCERA AVX (US): RECENT DEVELOPMENTS

TABLE 94. TAOGLAS (DUBLIN): FINANCIALS

TABLE 95. TAOGLAS (DUBLIN): PRODUCTS & SERVICES

TABLE 96. TAOGLAS (DUBLIN): RECENT DEVELOPMENTS

Charts

CHART. 1. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 2. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR ANTENNAE & CONNECTIVITY MODULES, BY GEOGRAPHY, 2021-2030 (USD BILLION)

CHART. 3. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR SENSORS, BY GEOGRAPHY, 2021-2030 (USD BILLION)

CHART. 4. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR CONNECTORS & SWITCHES, BY GEOGRAPHY, 2021-2030 (USD BILLION)

CHART. 5. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR LIGHTING SYSTEMS, BY GEOGRAPHY, 2021-2030 (USD BILLION)

CHART. 6. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR OTHERS, BY GEOGRAPHY, 2021-2030 (USD BILLION)

CHART. 7. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 8. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR LASER DIRECT STRUCTURING (LDS), 2021-2030 (USD BILLION)

CHART. 9. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR TWO-SHOT MOLDING, BY GEOGRAPHY, 2021-2030 (USD BILLION)

CHART. 10. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR FILM TECHNIQUES, 2021-2030 (USD BILLION)

CHART. 11. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY VERTICAL, 2021-2030 (USD BILLION)

CHART. 12. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR TELECOMMUNICATIONS, 2021-2030 (USD BILLION)

CHART. 13. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR CONSUMER ELECTRONICS, BY GEOGRAPHY, 2021-2030 (USD BILLION)

CHART. 14. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR AUTOMOTIVE, 2021-2030 (USD BILLION)

CHART. 15. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR MEDICAL, 2021-2030 (USD BILLION)

CHART. 16. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR INDUSTRIAL, 2021-2030 (USD BILLION)

CHART. 17. MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE FOR MILITARY & AEROSPACE, 2021-2030 (USD BILLION)

CHART. 18. NORTH AMERICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY COUNTRY, 2021-2030 (USD BILLION)

CHART. 19. NORTH AMERICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 20. NORTH AMERICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 21. U.S MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 22. U.S MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 23. CANADA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 24. CANADA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 25. MEXICO MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 26. MEXICO MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 27. EUROPE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY COUNTRY, 2021-2030 (USD BILLION)

CHART. 28. EUROPE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 29. EUROPE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 30. GERMANY MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 31. GERMANY MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 32. U.K MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 33. U.K MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 34. FRANCE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 35. FRANCE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 36. ITALY MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 37. ITALY MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 38. SPAIN MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY

PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 39. SPAIN MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 40. ROE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 41. ROE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 42. ASIA PACIFIC MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY COUNTRY, 2021-2030 (USD BILLION)

CHART. 43. ASIA PACIFIC MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 44. ASIA PACIFIC MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 45. CHINA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 46. CHINA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 47. INDIA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 48. INDIA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 49. JAPAN MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 50. JAPAN MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 51. REST OF APAC MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 52. REST OF APAC MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 53. LATIN AMERICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 54. LATIN AMERICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 55. BRAZIL MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

CHART. 56. BRAZIL MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)

CHART. 57. ARGENTINA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)

- CHART. 58. ARGENTINA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)
- CHART. 59. MIDDLE EAST AND AFRICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)
- CHART. 60. MIDDLE EAST AND AFRICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)
- CHART. 61. SAUDI ARABIA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)
- CHART. 62. SAUDI ARABIA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)
- CHART. 63. UAE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)
- CHART. 64. UAE MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)
- CHART. 65. REST OF MIDDLE EAST AND AFRICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PRODUCT TYPE, 2021-2030 (USD BILLION)
- CHART. 66. REST OF MIDDLE EAST AND AFRICA MOLDED INTERCONNECT DEVICE (MID) MARKET VALUE, BY PROCESS, 2021-2030 (USD BILLION)
- CHART. 67. MOLEX (US): FINANCIALS
- CHART. 68. MOLEX (US): PRODUCTS & SERVICES
- CHART. 69. MOLEX (US): RECENT DEVELOPMENTS
- CHART. 70. TE CONNECTIVITY (SWITZERLAND): FINANCIALS
- CHART. 71. TE CONNECTIVITY (SWITZERLAND): PRODUCTS & SERVICES
- CHART. 72. TE CONNECTIVITY (SWITZERLAND): RECENT DEVELOPMENTS
- CHART. 73. AMPHENOL CORPORATION (US): FINANCIALS
- CHART. 74. AMPHENOL CORPORATION (US): PRODUCTS & SERVICES
- CHART. 75. AMPHENOL CORPORATION (US): RECENT DEVELOPMENTS
- CHART. 76. LPKF LASER & ELECTRONICS (GERMANY): FINANCIALS
- CHART. 77. LPKF LASER & ELECTRONICS (GERMANY):PRODUCTS & SERVICES
- CHART. 78. LPKF LASER & ELECTRONICS (GERMANY):RECENT DEVELOPMENTS
- CHART. 79. HARTING (GERMANY): FINANCIALS
- CHART. 80. HARTING (GERMANY): PRODUCTS & SERVICES
- CHART. 81. HARTING (GERMANY): RECENT DEVELOPMENTS
- CHART. 82. ARLINGTON PLATING COMPANY (US): FINANCIALS
- CHART. 83. ARLINGTON PLATING COMPANY (US): PRODUCTS & SERVICES
- CHART. 84. ARLINGTON PLATING COMPANY (US): RECENT DEVELOPMENTS
- CHART. 85. MID SOLUTIONS (GERMANY).: FINANCIALS
- CHART. 86. MID SOLUTIONS (GERMANY).: PRODUCTS & SERVICES
- CHART. 87. MID SOLUTIONS (GERMANY).: RECENT DEVELOPMENTS

CHART. 88. 2E MECHATRONIC (GERMANY): FINANCIALS

CHART. 89. 2E MECHATRONIC (GERMANY): PRODUCTS & SERVICES

CHART. 90. 2E MECHATRONIC (GERMANY): RECENT DEVELOPMENTS

CHART. 91. KYOCERA AVX (US): FINANCIALS

CHART. 92. KYOCERA AVX (US): PRODUCTS & SERVICES

CHART. 93. KYOCERA AVX (US): RECENT DEVELOPMENTS

CHART. 94. TAOGLAS (DUBLIN): FINANCIALS

CHART. 95. TAOGLAS (DUBLIN): PRODUCTS & SERVICES

CHART. 96. TAOGLAS (DUBLIN): RECENT DEVELOPMENTS

I would like to order

Product name: Molded Interconnect Device (MID) Market based on by Product Type (Antennae & Connectivity, Sensor),by Process (Laser Direct Structuring, Two-shot Molding), by Industry (Consumer Electronics, Telecommunication, Medical) and Geography– Global Forecast up to 2030

Product link: <https://marketpublishers.com/r/M916E9AECAFBEN.html>

Price: US\$ 4,500.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/M916E9AECAFBEN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below
and fax the completed form to +44 20 7900 3970